



JOCDA3AB-W8

Rev.A.1.0

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The products are gate driver opto-couplers in a plastic WSOP8 package. The device consists of an infrared LED optically coupled to an integrated high-gain, high-speed photodetector IC chip. It provides guaranteed performance and specifications at temperature up to 110 . It is physically smaller and compliant with international safety standards for reinforced insulation. It thus provides a smaller footprint solution for applications that require safety standard certification. An internal noise shield provides a guaranteed common-mode transient immunity of ±35 kV/μs. It is ideal for small class IGBT and power MOSFET gate drive. The products are widely used in industrial inverters, IGBT gate drivers, MOSFET gate drivers, induction cooktop and home appliances.



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High isolation 7500 VRMS

Buffer logic type

Operating temperature range -40°C to 110°C

REACH & RoHS compliance

HBM: H3A; MM: M4; CDM: C3

CQC approved

VDE approved

UL approved

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LED	V _{CC} -V _{EE} (Positive Going)	V _{CC} -V _{EE} (Negative Going)	Output
OFF	0-30V	0-30V	Low
ON	0-12.1V	0-11.1V	Low
ON	12.1V-13.5V	11.1V-12.4V	TRANSITION
ON	13.5V-30V	12.4V-30V	HIGH

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Parameter		Symbol	Value	Unit
LED	Forward Current	I _F	50	mA
	Peak Forward Current	I _{FP}	1	A
	Reverse Voltage	V _R	6	V
	Power Dissipation	P _D	100	mW
Detector	Output Voltage	V _O	35	V
	Supply Voltage	V _{CC}	35	V
	Power Dissipation	P _C	400	mW
Isolation Voltage		V _{iso}	7500	Vrms
Operating Temperature		T _{opr}	-40~110	
Junction Temperature		T _j	125	
Storage Temperature		T _{stg}	-55~125	
Total Power Dissipation		P _{tot}	500	mW
Soldering Temperature		T _{sol}	260	

V \ u : 100µs pulse, 100Hz frequency

V \ u : AC for 1minute, R.H.=40~60%

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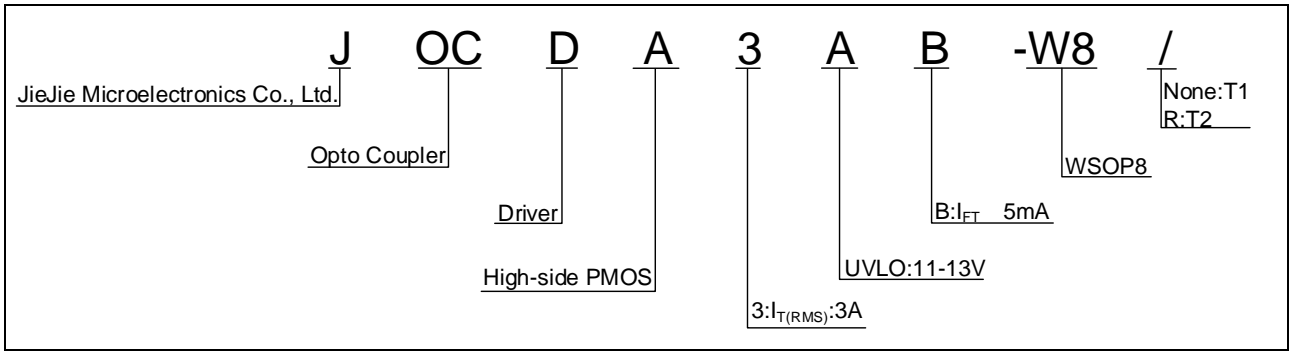
Parameter		Symbol	Condition	Min.	Typ.	Max.	Unit
Input	Forward Voltage	V _F	I _F =10mA	-	1.35	1.6	V
	Reverse Current	I _R	V _R =6V	-	-	1	µA
	Terminal Capacitance	C _t	V=0, f=1MHz	-	60	-	pF
Output	Peak High-level Output Current	I _{OPH}	V _O =V _{CC} -4V, Pulse width 50µs	-1	-	-	A
			V _O =V _{CC} -15V, Pulse width 10µs	-	-	-	A
	Peak Low-level Output Current	I _{OPL}	V _O =V _{EE} +2.5V, Pulse width 50µs V _O =V _{EE}	1	-	-	A

High Level Output Voltage	V _{OH}	I _F =5mA, V _{CC} =10V, I _O =-100mA	6	8.4	-	V
Low Level Output Voltage	V _{OL}	V _F =0.8V, V _{CC} =10V, I _O =100mA	-	0.3	1	V
Threshold Input Current	I _{FLH}	V _{CC} =15V, V _O 1V	-	1.2	5	mA
Threshold Input Voltage	V _{FHL}	V _{CC} =15V, V _O 1V	0.8	-	-	V
Supply Voltage	V _{CC}	-	15	-	30	V
UVLO Threshold	V _{UVLO+}	V _O 5V, I _F =10mA	12.1	12.8	13.5	V
	V _{UVLO-}	V _O 5V, I _F =10mA	11.1	11.8	12.4	V

of @#=@8'ch-#@@° u@V'

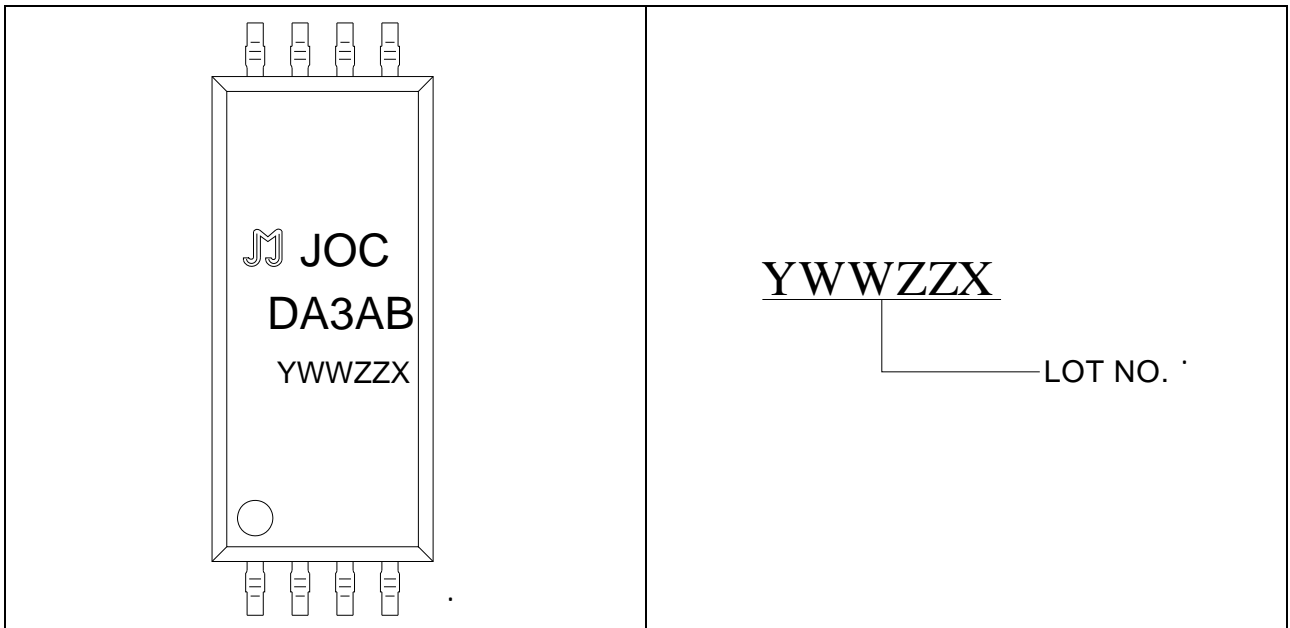
Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit	N
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None/R	1200Units/Reel

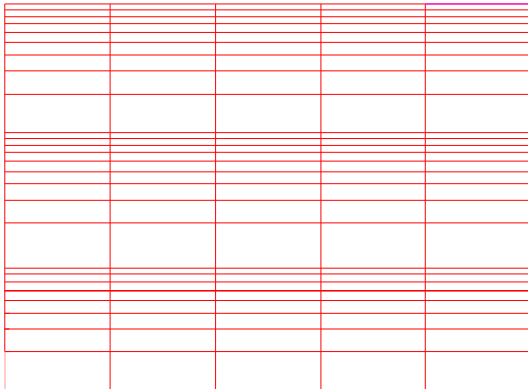
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FIG.1: Forward Current vs. Forward Voltage

FIG.2: Max. Allowable LED Forward Current vs. Ambient Temperature

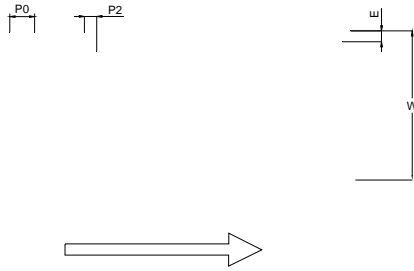


A red grid for plotting Forward Current vs. Forward Voltage. The grid consists of 10 columns and 15 rows.

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Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	13.50		13.70	0.531		0.539
B	6.15		6.35	0.242		0.250
C	0.10		0.30	0.004		0.012
D	3.50		3.70	0.138		0.146
E	14.71		15.31	0.579		0.603
F	0.52		1.02	0.020		0.040
G	16.36		16.86	0.644		0.664
H	0.10		0.40	0.004		0.016
I	3.65		0.00 0.60	0.144		0.156
J	0.307		0.607	0.012		0.024
K						

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Note:

1. Reflow soldering is recommended at the temperatures and times shown, no more than three times.
2. Avoid direct contact between the epoxy body and any tools or surfaces exceeding its maximum storage temperature.
3. Application of pressure on the epoxy body is prohibited at elevated temperatures. In spt on ts